



**THE DATASHEET OF  
10053826-100ABTLF**





Tous droits strictement réservés. Reproduction ou communication a des tiers interdite sous quelque forme que ce soit sans autorisation écrite du propriétaire. Propriete de c FCI. Droits de reproduction FCI.



All rights strictly reserved. Reproduction or issue to third parties in any form whatever is not permitted without written authority of FCI. Copyright FCI.

**NOTES :**

1. MATERIAL: HIGH TEMPERATURE THERMOPLASTIC, UL 94 V-O FLAME RETARDANT.  
TERMINAL: COPPER ALLOY.  
PLATING SPEC. AS BELOW :  
Ni 50u" UNDER PLATED.  
Au OR GXT 30u" OVER CONTACT AREA. (ONE SIDE)  
Tin 120u" OVER SOLDERING AREA.
2. PACKING SPEC. GS-14-924.
3. PRODUCT PERFORMANCE PER SPEC. GS-12-285.
4. PART NUMBER SCHEME: (EX. 10053826-100AB5MLF)  
10053826-X XX X X X X LF (LEAD FREE)

SPEC.	OPTION (CODE)	
	WITH (M)	WITHOUT ( )
MYLAR		
PACKING	TRAY (S)	TAPE & REEL (T) TUBE (P)
HSG COLOR	BLACK (B)	NATURE (N)
MOUNT SIDE	ABOVE (A)	
STAND-OFF	0 (00)	
PLATING	GOLD (1)	GXT (2)

**5. RoHS COMPATIBLE PRODUCT SPECIFICATIONS**

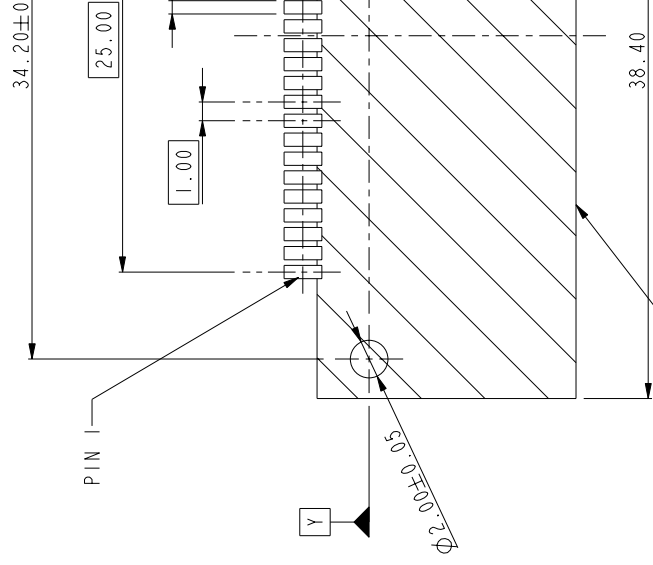
- a-PLATING:**  
 -"LF" MEANS THE PRODUCT IS LEAD-FREE, 2micro-meter MINIMUM MATTE TIN OVER 1.27micro-meter MINIMUM NICKEL UNDERPLATE.  
**b-MANUFACTURING PROCESS COMPATIBILITY**  
 -THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C±5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A REFLOW SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.

2

**3PDM: Rev:1**



☉  
 +++  
 catalog no

TOP MOUNT, 0  
 EXPRESSCARD\_HOST



## Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

-  [View 10053826-100ABTLF on WIN SOURCE](#)
-  [Amphenol Information](#)

## Optimize Your Supply Chain with WIN SOURCE Solutions

-  Global Sourcing Solution
-  Obsolete Management
-  Cost Control Management
-  Shortage Management
-  Alternative Solution
-  Excess Inventory Management